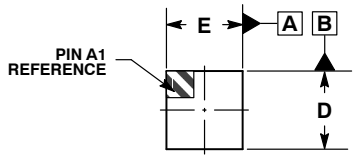
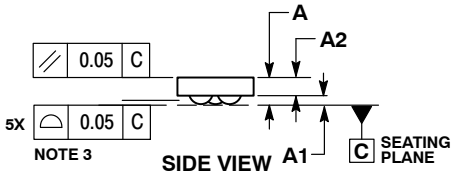
WLCSP5, 0.86x0.84
CASE 567DD
ISSUE D

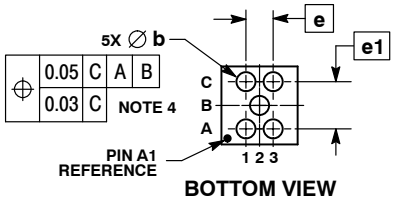
SCALE 4:1

DATE 14 JUL 2016



TOP VIEW





BOTTOM VIEW

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE CONTACT BALLS.
4. COPLANARITY APPLIES TO SPHERICAL CROWNS OF THE CONTACT BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.

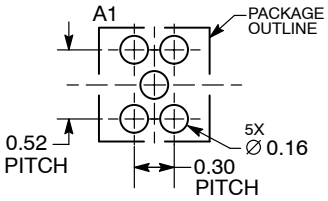
	MILLIMETERS		
DIM	MIN	NOM	MAX
A	---	---	0.39
A1	0.10	0.12	0.14
A2		0.23 REF	
b	0.14	0.16	0.18
D	0.84	0.86	0.88
E	0.82	0.84	0.86
e		0.30 BSC	
e1		0.52 BSC	

GENERIC MARKING DIAGRAM*

X = Specific Device Code
Y = Year
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking.
Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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